

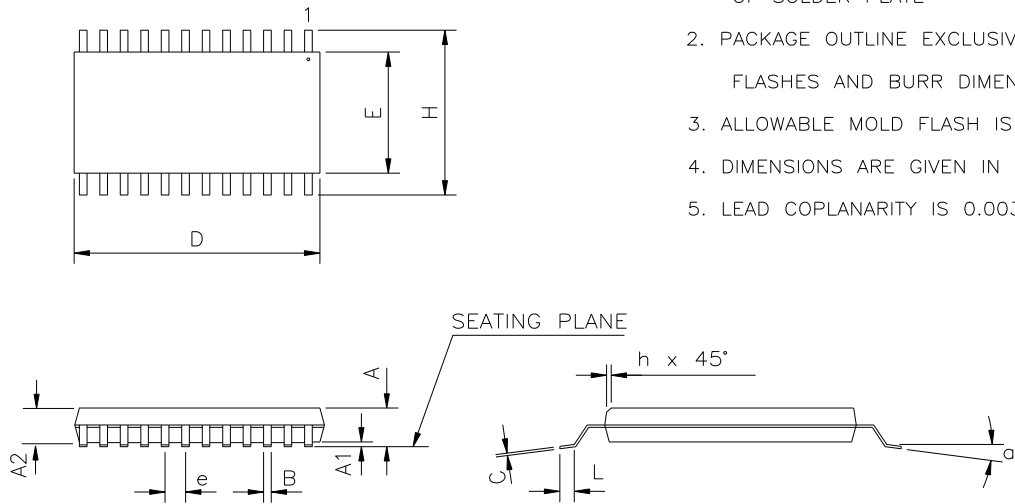
240 MIL TSSOP

Thin Shrink Small Outline Package (TSSOP)
Outline Gull Wing 48/56 Pin

PACKAGE INFORMATION

NOTES

1. LEAD WIDTH AND LEAD THICKNESS EXCLUSIVE OF SOLDER PLATE OF SOLDER PLATE
2. PACKAGE OUTLINE EXCLUSIVE OF MOLD FLASHES AND BURR DIMENSIONS
3. ALLOWABLE MOLD FLASH IS 5 MILS PER SIDE.
4. DIMENSIONS ARE GIVEN IN INCHES.
5. LEAD COPLANARITY IS 0.003 INCH MAX.



JEDEC #	MO-153ED		MO-153EE	
	48 LEAD		56 LEAD	
SYMBOL	Min	Max.	Min	Max.
A	0.0374	0.0472	0.0374	0.0472
A1	0.0019	0.0059	0.0019	0.0059
B	0.0070	0.0100	0.0070	0.0110
C	0.0039	0.0078	0.0039	0.0078
D	0.4881	0.4960	0.5472	0.5551
E	0.2362	0.2440	0.2362	0.2440
e	0.0196 BSC		0.0196 BSC	
H	0.3149	0.3228	0.3149	0.3228
L	0.0180	0.0300	0.0180	0.0300
α°	0°	8°	0°	8°

PREPARED BY	NK	REF. NO. DIM-TSOP-01	REV. NO.	SPEL SEMICONDUCTOR LIMITED INDIA
CHECKED BY	SP		1	
APPROVED BY	NJC		DATE 01.07.01	

